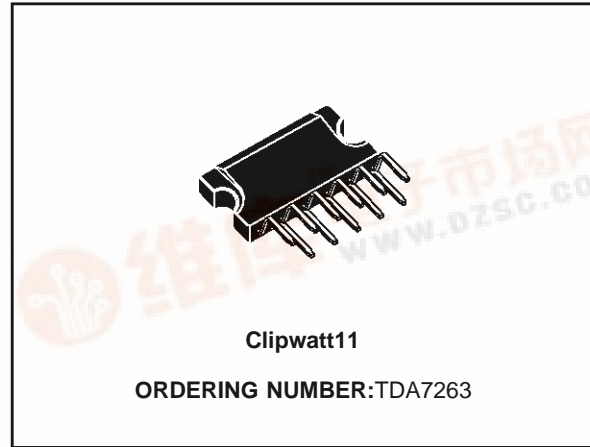




TDA7263

12 +12W STEREO AMPLIFIER WITH MUTING

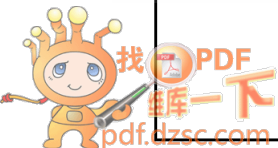
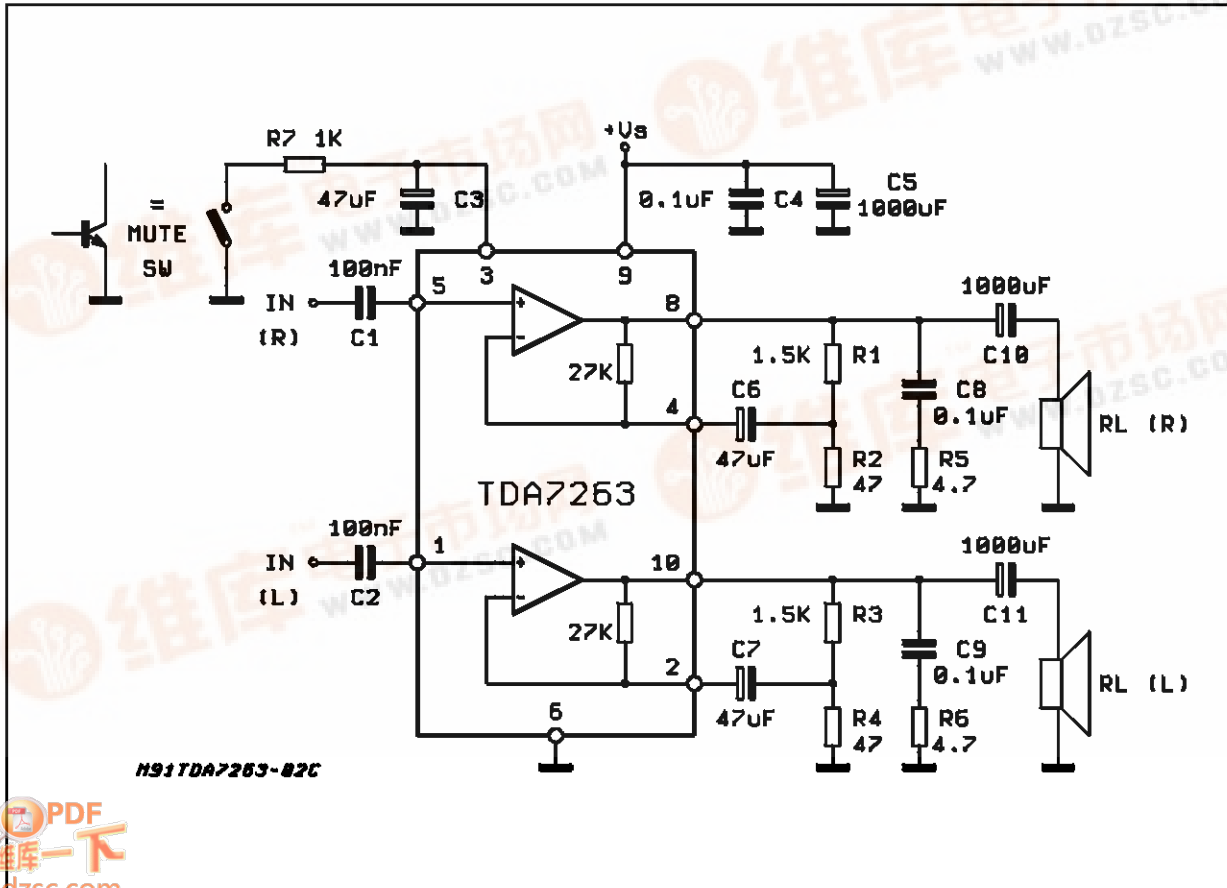
- WIDE SUPPLY VOLTAGE RANGE
- HIGH OUTPUT POWER
12+12W @ $V_S=28V$, $R_L = 8\Omega$, THD=10%
- MUTE FACILITY (POP FREE) WITH LOW CONSUMPTION
- AC SHORT CIRCUIT PROTECTION
- THERMAL OVERLOAD PROTECTION



DESCRIPTION

The TDA7263 is class AB dual audio power amplifier assembled in the new Clipwatt package, specially designed for high quality sound application as HI-FI music centers and stereo TV sets.

TEST AND APPLICATION CIRCUIT

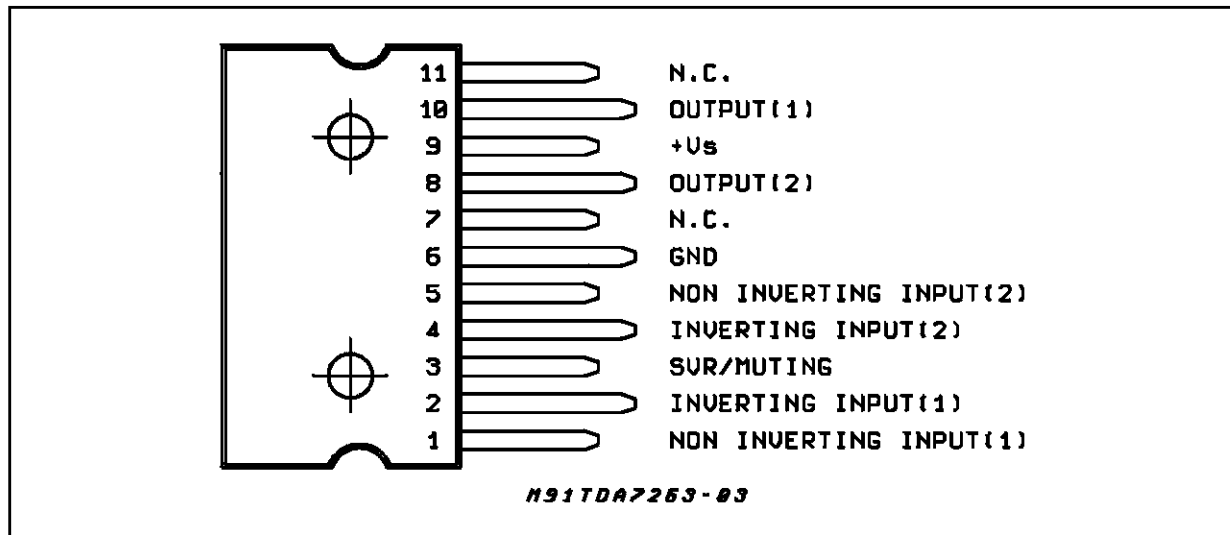


TDA7263

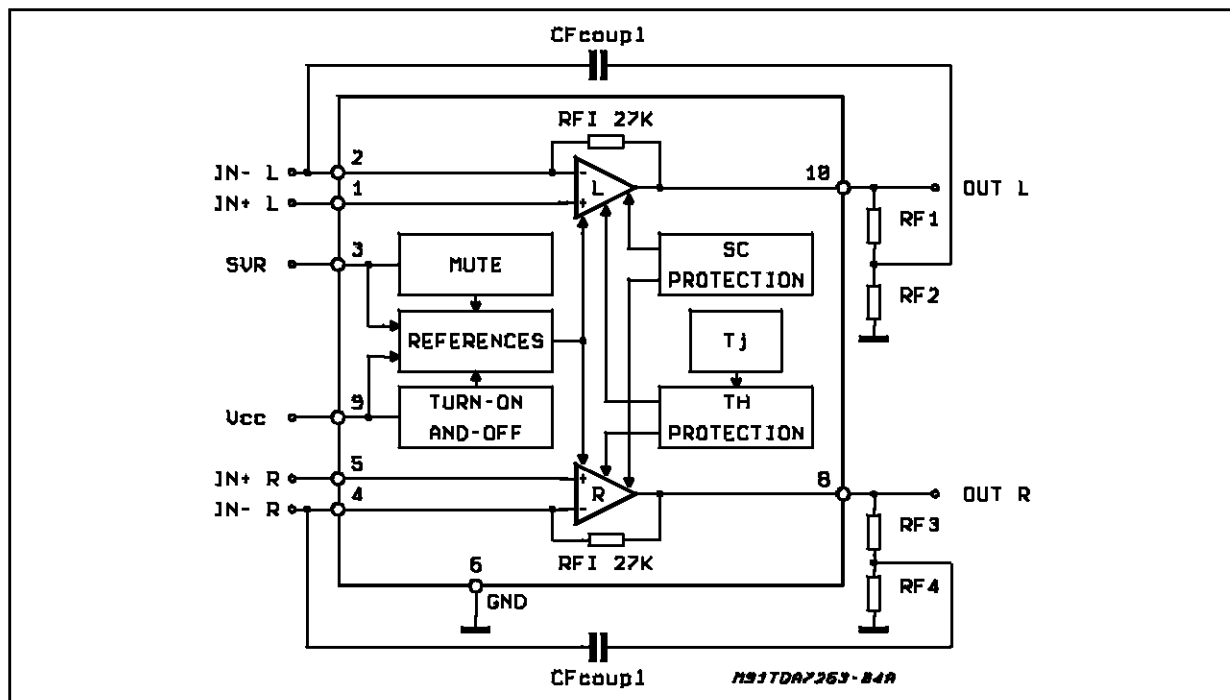
ABSOLUTE MAXIMUM RATINGS

| Symbol | Parameter | Value | Unit |
|----------------|---|------------|------------------|
| V_s | Supply Voltage | 35 | V |
| I_o | Output Peak Current (repetitive $f > 20\text{Hz}$) | 2.5 | A |
| I_o | Output Peak Current (non repetitive, $t = 100\mu\text{s}$) | 3.5 | A |
| P_{tot} | Total Power Dissipation ($T_{case} = 70^\circ\text{C}$) | 25 | W |
| T_{op} | Operating Temperature Range | 0 to 70 | $^\circ\text{C}$ |
| T_{stg, T_j} | Storage & Junction Temperature | -40 to 150 | $^\circ\text{C}$ |

PIN CONNECTION (Top view)



BLOCK DIAGRAM



THERMAL DATA

| Symbol | Parameter | Value | Unit |
|------------------|-------------------------------------|-------|---------------|
| $R_{th\ j-case}$ | Thermal resistance junction to case | Max 3 | $^{\circ}C/W$ |

ELECTRICAL CHARACTERISTICS (Refer to the stereo test and application circuit, $V_S = 28V$; $R_L = 8\Omega$; $G_v = 30dB$; $f = 1KHz$; $T_{amb} = 25^{\circ}C$ unless otherwise specified.)

| Symbol | Parameter | Test Condition | Min. | Typ. | Max. | Unit |
|----------------------|---|---|------|-----------|------------|-------------|
| V_S | Supply Voltage | | 10 | | 32 | V |
| V_O | Quiescent Output Voltage | | | 13.5 | | V |
| I_q | Total Quiescent Current | | | 70 | 95 | mA |
| P_O | Output Power (RMS) | $d = 10\%$ $T_{amb} = 85^{\circ}C$ $d = 1\%$ | 10 | 12 9.5 | | W W |
| d | Total Harmonic Distortion | $P_O = 1W, f = 1kHz$ $f = 100Hz\ to\ 10KHz; P_O = 0.1\ to\ 8W$ | | 0.02 | 0.2 0.5 | % |
| CT | Cross Talk | $R_S = 10K\Omega; f = 1KHz$ | | 70 | | dB |
| | | $R_S = 10K\Omega; f = 10KHz$ | | 60 | | dB |
| R_i | Input Resistance | | 100 | 200 | | $K\Omega$ |
| f_L | Low Frequency Roll-off (-3dB) | | | 40 | | Hz |
| f_H | High Frequency Roll-off (-3dB) | | | 80 | | KHz |
| eN | Total Input Noise Voltage | A Curve; $R_S = 10K\Omega$ | | 1.5 | | mV |
| | | $f = 22Hz\ to\ 22KHz; R_S = 10K\Omega$ | | 3 | 10 | μV |
| SVR | Supply Voltage Rejection (each channel) | $R_S = 10K\Omega; f = 100Hz; V_r = 0.5V$ | 45 | 60 | | dB |
| T_j | Thermal Shutdown Junction Temperature | | | 145 | | $^{\circ}C$ |
| MUTE FUNCTION | | | | | | |
| V_{T_MUTE} | Mute Threshold | | 1 | 1.6 | | V |
| V_{T_PLAY} | Play Threshold | | | 4.5 | | V |
| ATT_{AM} | Mute Attenuation | | 70 | 100 | | dB |
| I_{q_MUTE} | Quiescent Current @ Mute | | | 7 | 10 | mA |

TYPICAL CHARACTERISTICS (referred to the typical Application Circuit, $V_S = 28V$, $R_L = 8\Omega$, unless otherwise specified)

Figure 1: Output Power vs. Supply Voltage

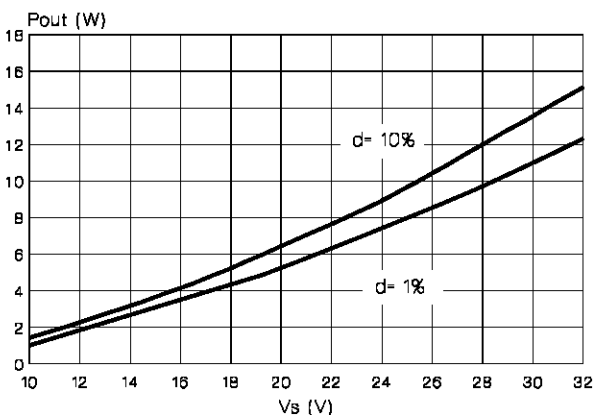


Figure 2: Distortion vs. Output Power

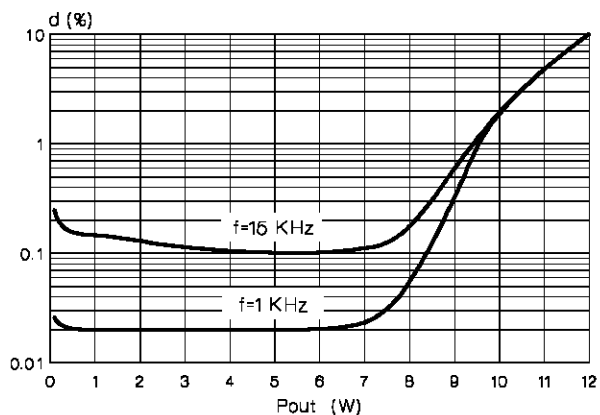


Figure 3: Quiescent Current vs. Supply Voltage

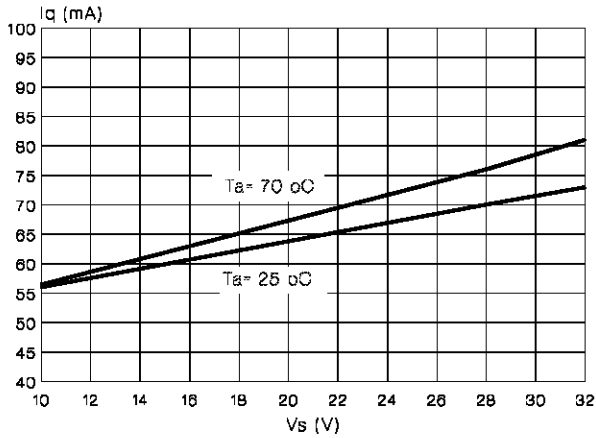


Figure 4: Supply Voltage Rejection vs. Frequency

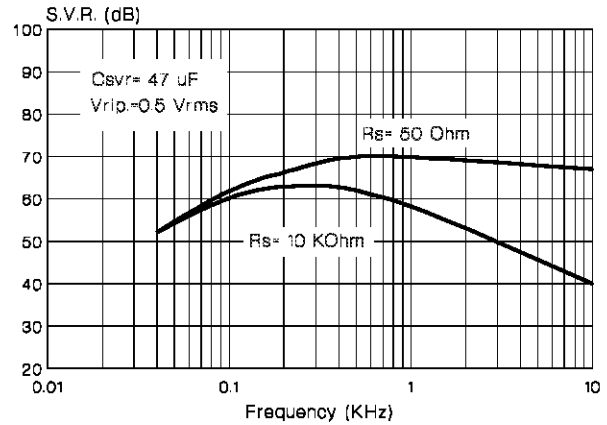


Figure 5: Crosstalk vs. Frequency

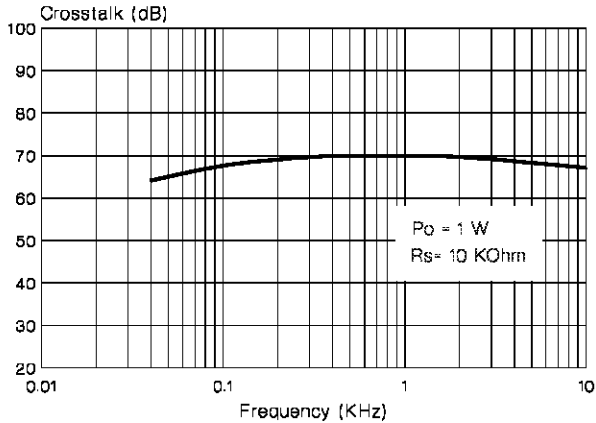


Figure 6: Output Attenuation & Quiescent Current vs. V_{pin3}

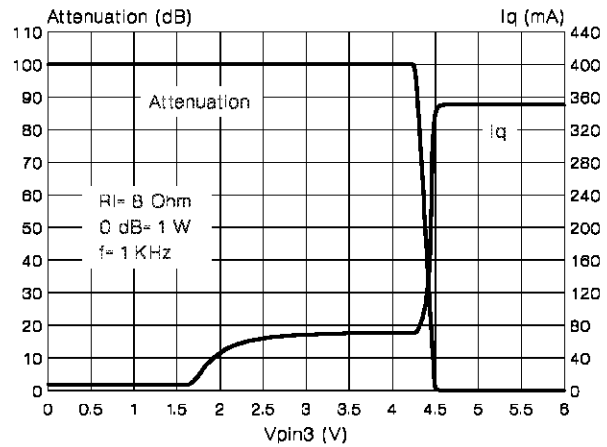


Figure 7: Total Power Dissipation vs. Output Power

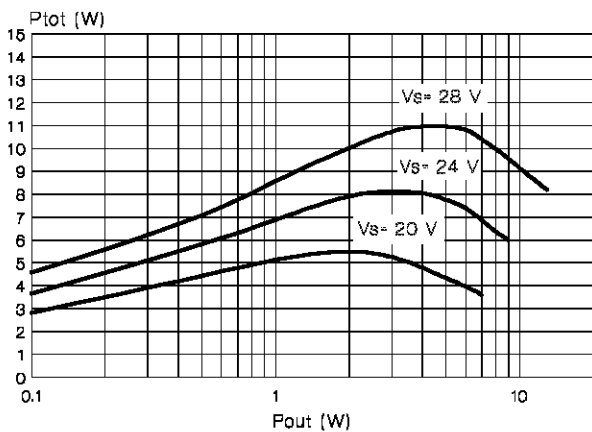
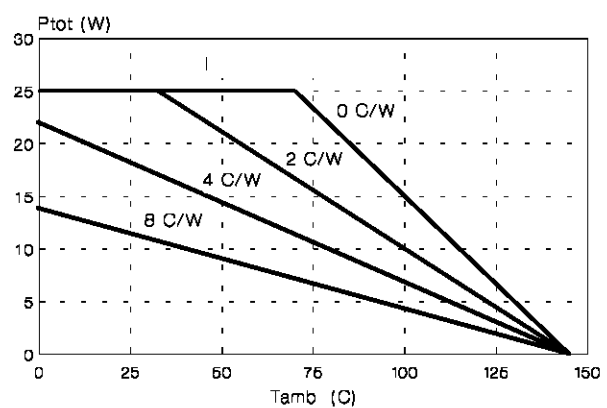


Figure 8: Maximum allowable Power dissipation vs. Ambient Temperature



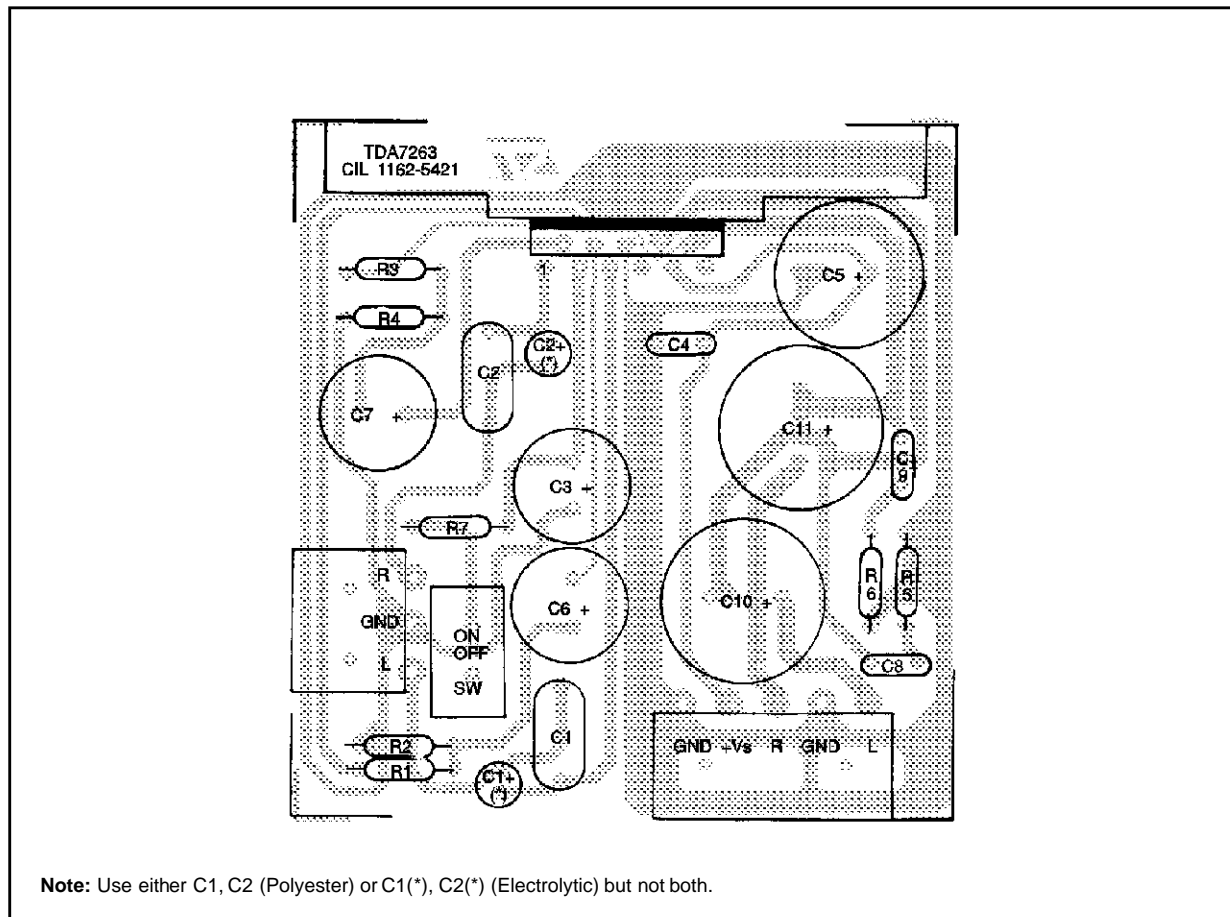
APPLICATION SUGGESTION

The recommended values of the components are those shown on the typical application circuit. Different values can be used; the following table can help the designer.

| Component | Recomm. Value | Purpose | Larger Than | Smaller Than |
|-------------|---------------|--|--------------------------------|--|
| R1 and R3 | 1.5KΩ | Close loop gain setting (*) | Increase of gain | Decrease of gain |
| R2 and R4 | 47Ω | Close loop gain setting (*) | Decrease of gain | Increase of gain |
| R5 and R6 | 4.7Ω | Frequency stability | Danger of oscillations | |
| C1 and C2 | 100nF | Input DC decoupling | Higher SVR | Higher low frequency cutoff |
| C3 | 47μF | - Ripple Rejection - Mute time constant | Increase of the Switch-on time | - Degradation of SVR - Worse turn-off pop by muting |
| C4 | 100nF | Supply Voltage Bypass | | Danger of oscillations |
| C5 | 1000μF | Supply Voltage Bypass | | |
| C6 and C7 | 47μF | Feedback input DC decoupling | Increase of the Switch-on time | Danger of Switch-on time |
| C8 and C9 | 0.1μF | Frequency stability | | Danger of oscillations |
| C10 and C11 | 1000μF | Output DC decoupling | | Higher low-frequency cut-off |

(*) Closed loop gain must be higher than 26dB

Figure 9: P.C. Board and Component Layout (1:1 scale)



BUILT-IN PROTECTION SYSTEMS

THERMAL SHUT-DOWN

The presence of a thermal limiting circuit offers the following advantages:

- 1-an overload on the output (even if it is permanent), or an excessive ambient temperature can be easily withstood.
- 2-the heatsink can have a smaller factor of safety compared with that of a conventional circuit. There is no device damage in the case of excessive junction temperature; if for any reason the junction temperature increases up to 145°C. the thermal shutdown simply re-

duces the output power and therefore the power dissipation.

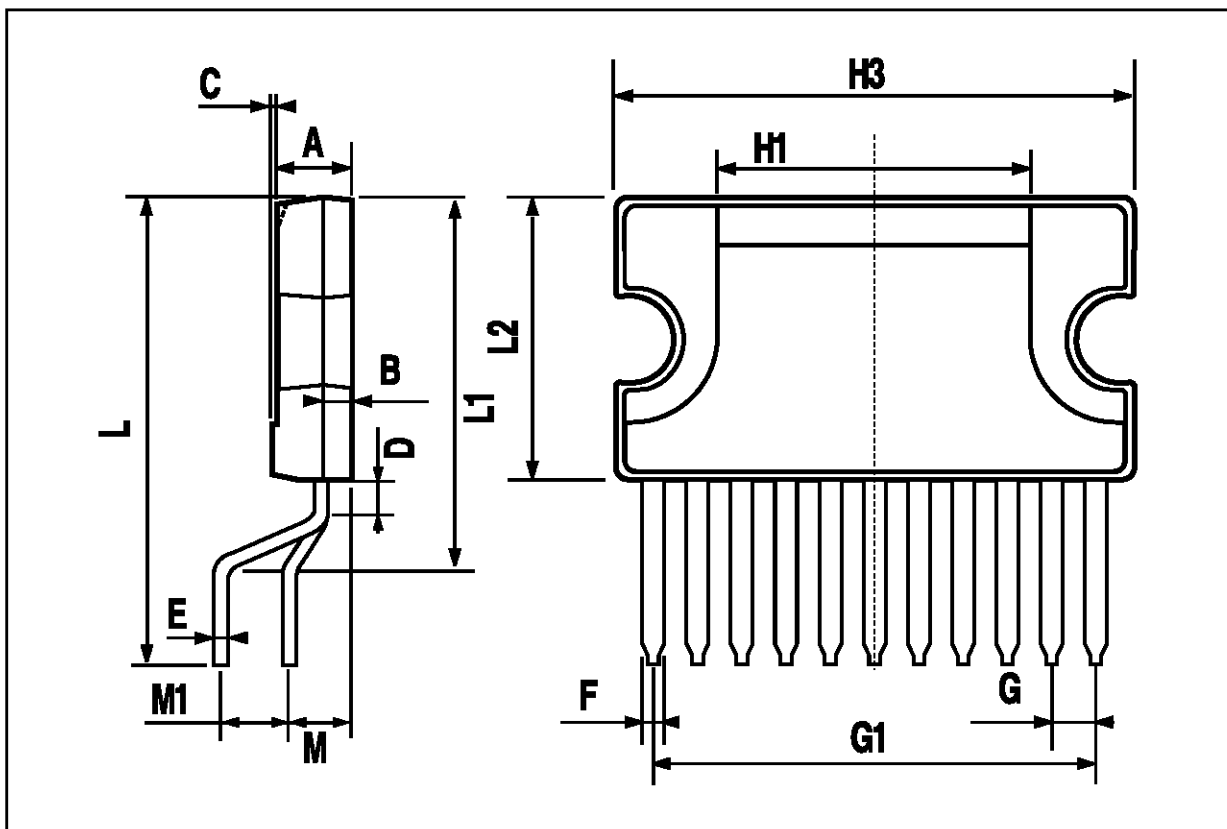
The maximum allowable power dissipation depends upon the thermal resistance junction-ambient. Figure 8 shows the dissipable power as a function of ambient temperature for different heatsink thermal resistance.

SHORT CIRCUIT (AC CONDITIONS)

The TDA7263 can withstand accidental short circuits across the speaker made by a wrong connection during normal play operation.

CLIPWATT11 PACKAGE MECHANICAL DATA

| DIM. | mm | | | inch | | |
|------|------|-------|------|------|-------|-------|
| | MIN. | TYP. | MAX. | MIN. | TYP. | MAX. |
| A | | | 3.10 | | | 0.122 |
| B | | | 1.10 | | | 0.04 |
| C | | 0.15 | | | 0.006 | |
| D | | 1.50 | | | 0.059 | |
| E | | 0.52 | | | 0.02 | |
| F | | 0.80 | | | 0.03 | |
| G | | 1.70 | | | 0.066 | |
| G1 | | 17.00 | | | 0.66 | |
| H1 | | 12.00 | | | 0.48 | |
| H3 | | 20.00 | | | 0.79 | |
| L | | 17.90 | | | 0.70 | |
| L1 | | 14.40 | | | 0.57 | |
| L2 | | 11.00 | | | 0.43 | |
| M | | 2.54 | | | 0.1 | |
| M1 | | 2.54 | | | 0.1 | |



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